

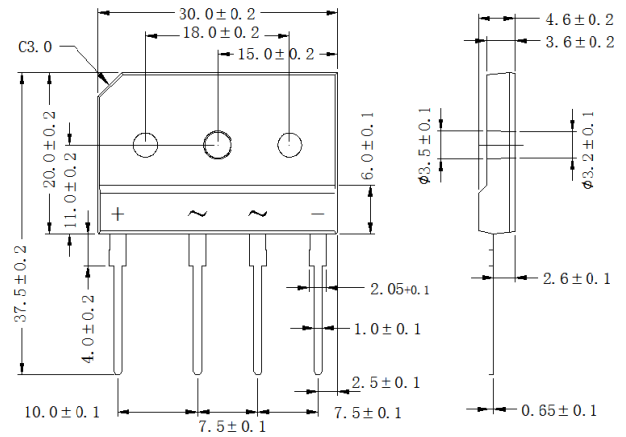


Features

- Ideal for printed circuit board mounting
- The plastic material used carries Underwriters Laboratory flammability recognition 94V-0
- Built-in printed circuit board stand-offs
- High case dielectric strength
- High temperature soldering guaranteed 260 C /5 seconds at 5 lbs (2.3kg) tension

Mechanical Data

- Case: Reliable low cost construction utilizing molded plastic technique
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Mounting Position: Any



Dimensions in inches and (millimeters)

Maximum Ratings & Thermal Characteristics

CHARACTERISTICS	SYMBOL	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	30	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ T _C =100 C (with heatsink Note 2) (without heatsink)	I _{F(AV)}	35.0 3.5							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I _{FSM}	400							A
Maximum Forward Voltage at 10.0A DC	V _F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ T _J =25 C @ T _J =125 C	I _R	10 500							uA
Typical Thermal Resistance (Note2)	R _{θJC}	1.5							°C/W
Operating Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

NOTES: 1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
2.Device mounted on 300mm*300mm*1.6mm cu plate heatsink.



■ Rating and Characteristic Curves (TA=25°C Unless otherwise noted)

FIG.1-FORWARD CURRENT DERATING CURVE

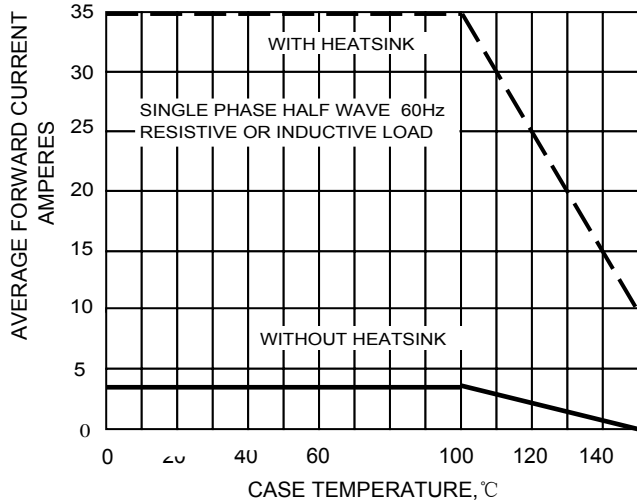


FIG.2-MAXMUN NON-REPETITIVE SURGE CURRENT

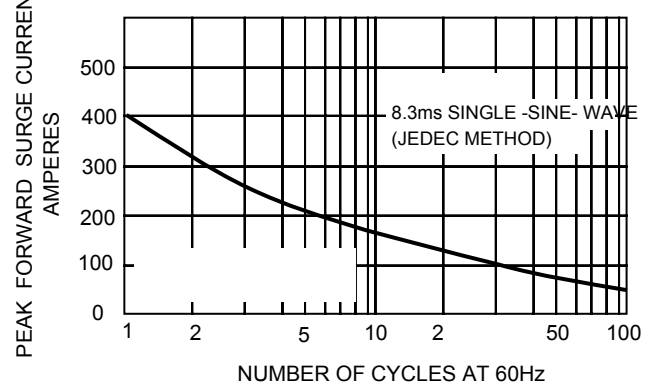


FIG.3-TYPICAL JUNCTION CAPACITANCE

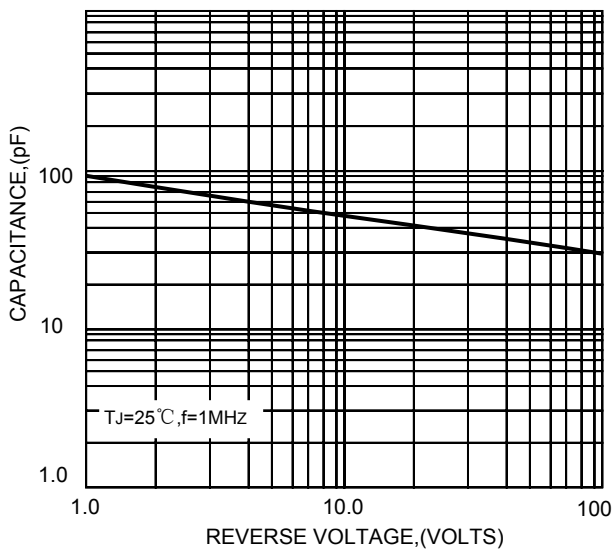


FIG.4-TYPICAL FORWARD CHARACTERISTICS

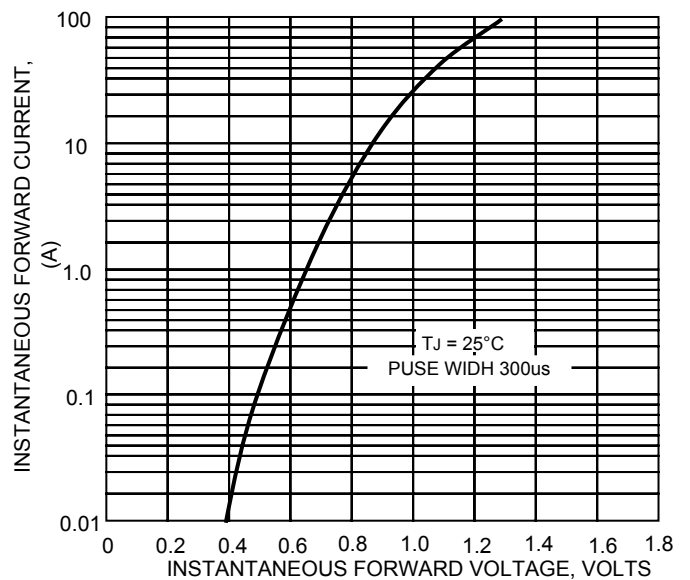


FIG.5-TYPICAL REVERSE CHARACTERISTICS

